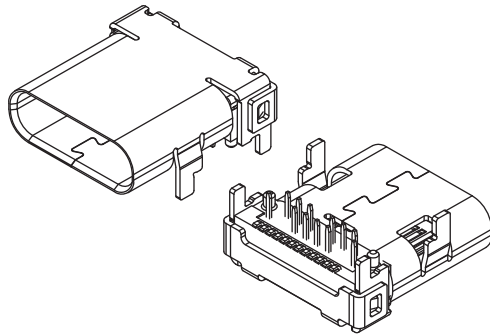


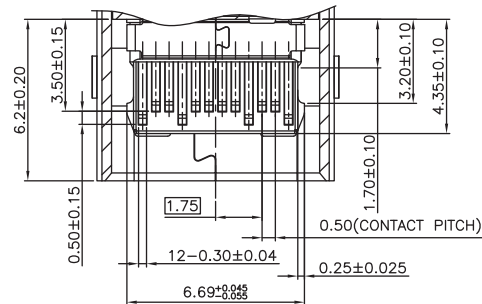
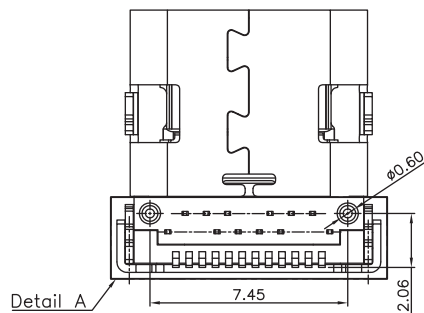
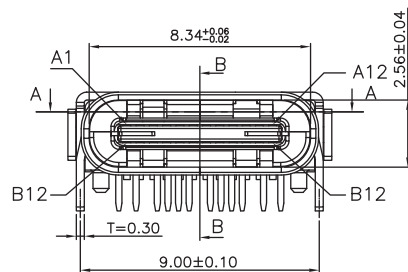
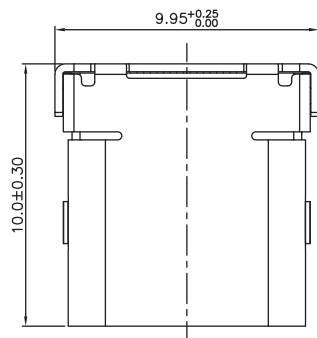
DATASHEET



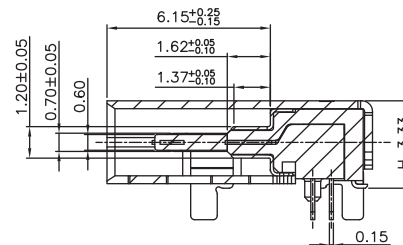
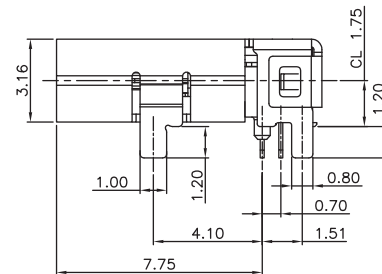
Technical data:

Insulating material:	LCP, UL 94V-0, Colour: Black
Contact material:	Copper Alloy
Plating contact:	Gold flash on contact area, Tin 2,5 µm min. on solder area
Shell:	SUS304-H, T = 0,30±0,03 mm
Plating shell:	Nickel 1,25 µm all over
Shield:	SUS304-H, T = 0,12±0,03 mm
Rated current:	5 Amp. for VBUS / 1,25 Amp. for VCONN
Rated voltage:	5 V _{AC} max.
Insulating resistance:	100 MOhm min.
Contact resistance:	40 mOhm max.
Withstand voltage:	100 V _{AC}
Operating temperature:	-40°C to +85°C
Max. processing temp.:	260°C for 10 seconds
Durability:	10.000 cycles
Insertion:	5 - 20 N
Extraction:	8 - 20 N

RoHS compliant



SECTION B-B



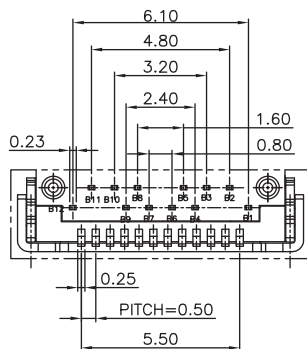
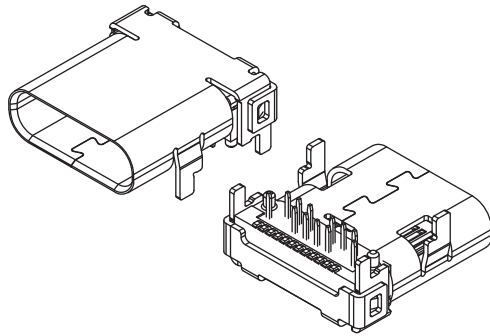
SECTION A-A

Plating: S = Sel. Au

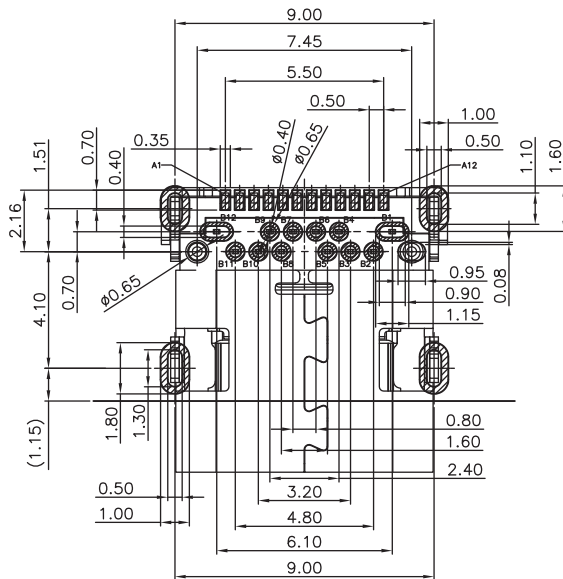
Packaging: R = Reel

Order code: **719-1-S-XR0**Part No.: **12071900004_**

DATASHEET



Detail A



RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)

TOLERANCE FOR PCB LAYOUT IS ± 0.05

KEEP OUT AREA

Plating: S = Sel. Au

Packaging: R = Reel

Order code: **719-1-S-XR0**Part No.: **12071900004_**

Technical data:

Insulating material:	LCP, UL 94V-0, Colour: Black
Contact material:	Copper Alloy
Plating contact:	Gold flash on contact area, Tin 2,5 μm min. on solder area
Shell:	SUS304-H, T = 0,30 $\pm$ 0,03 mm
Plating shell:	Nickel 1,25 μm all over
Shield:	SUS304-H, T = 0,12 $\pm$ 0,03 mm
Rated current:	5 Amp. for VBUS / 1,25 Amp. for VCONN
Rated voltage:	5 V _{AC} max.
Insulating resistance:	100 MOhm min.
Contact resistance:	40 mOhm max.
Withstand voltage:	100 V _{AC}
Operating temperature:	-40°C to +85°C
Max. processing temp.:	260°C for 10 seconds
Durability:	10.000 cycles
Insertion:	5 - 20 N
Extraction:	8 - 20 N

RoHS compliant

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

PIN	Signal Name	Description	PIN	Signal Name	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSTXp1	Positive half of first SuperSpeed TX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSTXn1	Negative half of first SuperSpeed TX differential pair
A4	VBUS	Bus Power	B9	VBUS	Bus Power
A5	CC1	Configuration Channel	B8	CC1	Configuration Channel
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dp1	Positive half of the USB 2.0 differential pair-Position 1
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dn1	Negative half of the USB 2.0 differential pair-Position 1
A8	RFU1	Reserved for Future Use (RFU)	B5	RFU1	Reserved for Future Use (RFU)
A9	VBUS	Bus Power	B4	VBUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSRXn2	Negative half of second SuperSpeed RX differential pair
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSRXp2	Positive half of second SuperSpeed RX differential pair
A12	GND	Ground return	B1	GND	Ground return